# **Retriggerable Monostable Multivibrators**

These dc triggered multivibrators feature pulse width control by three methods. The basic pulse width is programmed by selection of external resistance and capacitance values. The LS122 has an internal timing resistor that allows the circuits to be used with only an external capacitor. Once triggered, the basic pulse width may be extended by retriggering the gated low-level-active (A) or high-level-active (B) inputs, or be reduced by use of the overriding clear.

- Overriding Clear Terminates Output Pulse
- Compensated for V<sub>CC</sub> and Temperature Variations
- DC Triggered from Active-High or Active-Low Gated Logic Inputs
- Retriggerable for Very Long Output Pulses, up to 100% Duty Cycle
- Internal Timing Resistors on LS122

## **GUARANTEED OPERATING RANGES**

Symbol	Parameter	Min	Тур	Мах	Unit
V <sub>CC</sub>	Supply Voltage	4.75	5.0	5.25	V
T <sub>A</sub>	Operating Ambient Temperature Range	0	25	70	°C
I <sub>OH</sub>	Output Current – High			-0.4	mA
I <sub>OL</sub>	Output Current – Low			8.0	mA
R <sub>ext</sub>	External Timing Resistance	5.0		260	kΩ
C <sub>ext</sub>	External Capacitance	No Restriction			
R <sub>ext</sub> /C <sub>ext</sub>	Wiring Capacitance at R <sub>ext</sub> /C <sub>ext</sub> Terminal			50	pF



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# LOW POWER SCHOTTKY



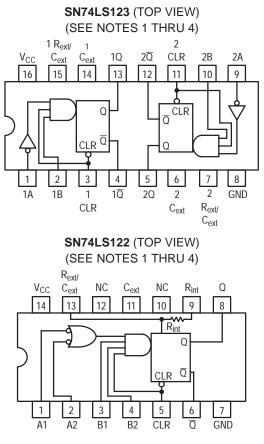




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## ORDERING INFORMATION

Device	Package	Shipping
SN74LS122N	14 Pin DIP	2000 Units/Box
SN74LS122D	14 Pin	2500/Tape & Reel
SN74LS123N	16 Pin DIP	2000 Units/Box
SN74LS123D	16 Pin	2500/Tape & Reel



NC - NO INTERNAL CONNECTION.

#### NOTES:

1. An external timing capacitor may be connected between  $C_{\text{ext}}$  and  $R_{\text{ext}}/C_{\text{ext}}$  (positive).

2. To use the internal timing resistor of the LS122, connect  $R_{int}$  to  $V_{CC}.$ 

3. For improved pulse width accuracy connect an external resistor between  $R_{ext}/C_{ext}$  and  $V_{CC}$  with  $R_{int}$  open-circuited. 4. To obtain variable pulse widths, connect an external variable resistance between  $R_{int}/C_{ext}$  and  $V_{CC}$ .

#### LS122 FUNCTIONAL TABLE

	INPUTS					
CLEAR	A1	A2	B1	B2	Q	Q
L	Х	Х	Х	Х	L	Н
Х	н	Н	Х	Х	L	н
Х	Х	Х	L	Х	L	н
Х	Х	Х	Х	L	L	н
н	L	Х	$\uparrow$	Н	л	υ
н	L	Х	Н	$\uparrow$	л	U U
н	Х	L	$\uparrow$	Н	л	ר ער ו
н	Х	L	Н	$\uparrow$	л	υ
н	н	$\downarrow$	Н	Н	л	υ
н	$\downarrow$	$\downarrow$	Н	Н	л	υ
н	$\downarrow$	Н	Н	Н	л	l u
$\uparrow$	L	Х	Н	Н	л	U U
↑	Х	L	Н	Н	Л	ъ

#### TYPICAL APPLICATION DATA

The output pulse  $t_W$  is a function of the external components,  $C_{ext}$  and  $R_{ext}$  or  $C_{ext}$  and  $R_{int}$  on the LS122. For values of  $C_{ext} \ge 1000$  pF, the output pulse at  $V_{CC} = 5.0$  V and  $V_{RC} = 5.0$  V (see Figures 1, 2, and 3) is given by

 $t_W = K R_{ext} C_{ext}$  where K is nominally 0.45

If  $C_{ext}$  is on pF and  $R_{ext}$  is in k $\Omega$  then t<sub>W</sub> is in nanoseconds.

The  $C_{ext}$  terminal of the LS122 and LS123 is an internal connection to ground, however for the best system performance  $C_{ext}$  should be hard-wired to ground.

Care should be taken to keep  $R_{ext}$  and  $C_{ext}$  as close to the monostable as possible with a minimum amount of inductance between the  $R_{ext}/C_{ext}$  junction and the  $R_{ext}/C_{ext}$  pin. Good groundplane and adequate bypassing should be designed into the system for optimum performance to ensure that no false triggering occurs.

It should be noted that the  $C_{ext}$  pin is internally connected to ground on the LS122 and LS123, but not on the LS221. Therefore, if  $C_{ext}$  is hard-wired externally to ground, substitution of a LS221 onto a LS123 socket will cause the LS221 to become non-functional.

The switching diode is not needed for electrolytic capacitance application and should not be used on the LS122 and LS123.

To find the value of K for  $C_{ext} \ge 1000$  pF, refer to Figure 4. Variations on  $V_{CC}$  or  $V_{RC}$  can cause the value of K to change, as can the temperature of the LS123, LS122.

**LS123 FUNCTIONAL TABLE** 

INF	INPUTS				
CLEAR	Α	В	Q	Q	
L	Х	Х	L	Н	
Х	н	Х	L	Н	
X	Х	L	L	Н	
н	L	$\uparrow$	л.	പ	
н	$\downarrow$	Н	Л	ഹ	
↑	L	Н	л.	U	

Figures 5 and 6 show the behavior of the circuit shown in Figures 1 and 2 if separate power supplies are used for  $V_{CC}$  and  $V_{RC}$ . If  $V_{CC}$  is tied to  $V_{RC}$ , Figure 7 shows how K will vary with  $V_{CC}$  and temperature. Remember, the changes in  $R_{ext}$  and  $C_{ext}$  with temperature are not calculated and included in the graph.

As long as  $C_{ext} \ge 1000$  pF and  $5K \le R_{ext} \le 260K$ , the change in K with respect to  $R_{ext}$  is negligible.

If  $C_{ext} \le 1000$  pF the graph shown on Figure 8 can be used to determine the output pulse width. Figure 9 shows how K will change for  $C_{ext} \le 1000$  pF if  $V_{CC}$  and  $V_{RC}$  are connected to the same power supply. The pulse width  $t_W$  in nanoseconds is approximated by

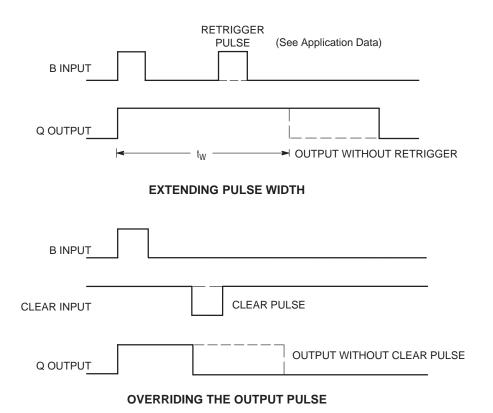
 $t_W = 6 + 0.05 C_{ext} (pF) + 0.45 R_{ext} (k\Omega) C_{ext} + 11.6 R_{ext}$ 

In order to trim the output pulse width, it is necessary to include a variable resistor between  $V_{CC}$  and the  $R_{ext}/C_{ext}$  pin or between  $V_{CC}$  and the  $R_{ext}$  pin of the LS122. Figure 10, 11, and 12 show how this can be done.  $R_{ext}$  remote should be kept as close to the monostable as possible.

Retriggering of the part, as shown in Figure 3, must not occur before  $C_{ext}$  is discharged or the retrigger pulse will not have any effect. The discharge time of  $C_{ext}$  in nanoseconds is guaranteed to be less than 0.22  $C_{ext}$  (pF) and is typically 0.05  $C_{ext}$  (pF).

For the smallest possible deviation in output pulse widths from various devices, it is suggested that  $C_{ext}$  be kept  $\geq 1000 \text{ pF}.$ 

## WAVEFORMS



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			Limits						
Symbol	Parameter		Min	Тур	Мах	Unit	Test C	onditions	
V <sub>IH</sub>	Input HIGH Voltage		2.0			V	Guaranteed Inp All Inputs	Guaranteed Input HIGH Voltage for All Inputs	
V <sub>IL</sub>	Input LOW Voltage				0.8	V	Guaranteed Inp All Inputs	ut LOW Voltage for	
V <sub>IK</sub>	Input Clamp Diode Voltage			-0.65	-1.5	V	$V_{CC} = MIN, I_{IN} =$	= – 18 mA	
V <sub>OH</sub>	Output HIGH Voltage		2.7	3.5		V	$V_{CC}$ = MIN, $I_{OH}$ = MAX, $V_{IN}$ = $V_{IH}$ or $V_{IL}$ per Truth Table		
				0.25	0.4	V	I <sub>OL</sub> = 4.0 mA	$V_{CC} = V_{CC} MIN,$	
V <sub>OL</sub>	Output LOW Voltage			0.35	0.5	V	I <sub>OL</sub> = 8.0 mA	V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> per Truth Table	
					20	μA	V <sub>CC</sub> = MAX, V <sub>IN</sub>	= 2.7 V	
Iн	Input HIGH Current				0.1	mA	V <sub>CC</sub> = MAX, V <sub>IN</sub>	<sub>1</sub> = 7.0 V	
IIL	Input LOW Current				-0.4	mA	$V_{CC} = MAX, V_{IN} = 0.4 V$		
I <sub>OS</sub>	Short Circuit Current (Note 1	)	-20		-100	mA	V <sub>CC</sub> = MAX		
	Bower Supply Current	LS122			11		V <sub>CC</sub> = MAX		
Icc	Power Supply Current	LS123			20	mA			

#### DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

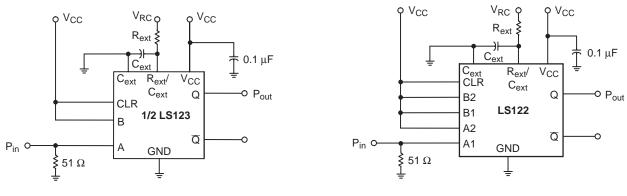
Note 1: Not more than one output should be shorted at a time, nor for more than 1 second.

## AC CHARACTERISTICS (T<sub>A</sub> = 25°C, V<sub>CC</sub> = 5.0 V)

		Limits					
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions	
t <sub>PLH</sub>	Propagation Delay, A to Q		23	33			
t <sub>PHL</sub>	Propagation Delay, A to $\overline{Q}$		32	45	ns	$C_{ext} = 0$	
t <sub>PLH</sub>	Propagation Delay, B to Q		23	44		C <sub>ext</sub> = 0 C <sub>L</sub> = 15 pF	
t <sub>PHL</sub>	Propagation Delay, B to $\overline{Q}$		34	56	ns	$R_{ext} = 5.0 \ k\Omega$	
t <sub>PLH</sub>	Propagation Delay, Clear to $\overline{Q}$		28	45		$R_L = 2.0 \text{ k}\Omega$	
t <sub>PHL</sub>	Propagation Delay, Clear to Q		20	27	ns		
t <sub>W min</sub>	A or B to Q		116	200	ns	C <sub>ext</sub> = 1000 pF, R <sub>ext</sub> = 10 kΩ,	
t <sub>W</sub> Q	A to B to Q	4.0	4.5	5.0	μs	$C_{L} = 15 \text{ pF}, R_{L} = 2.0 \text{ k}\Omega$	

## AC SETUP REQUIREMENTS (T\_A = 25°C, V\_{CC} = 5.0 V)

		Limits				
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
t <sub>W</sub> Pulse Width		40			ns	







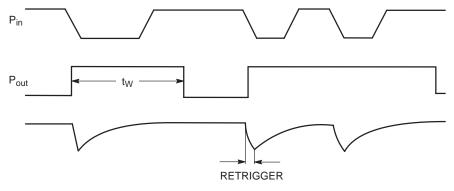


Figure 3.

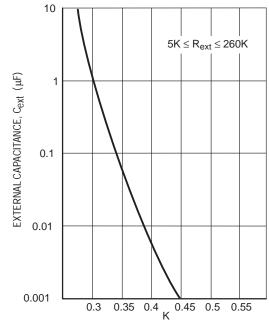
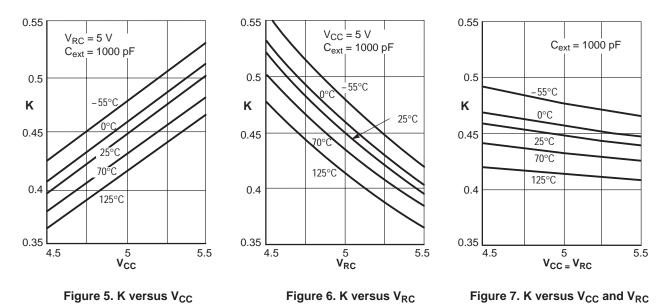


Figure 4.



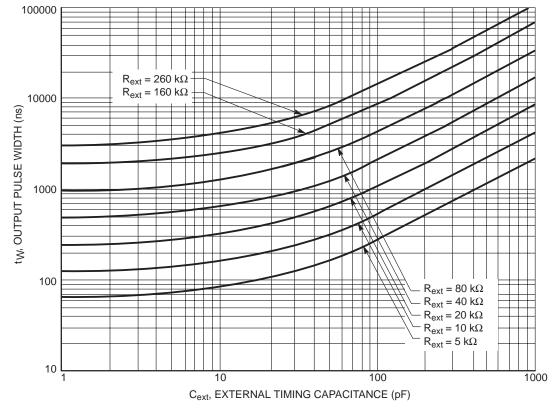


Figure 8.

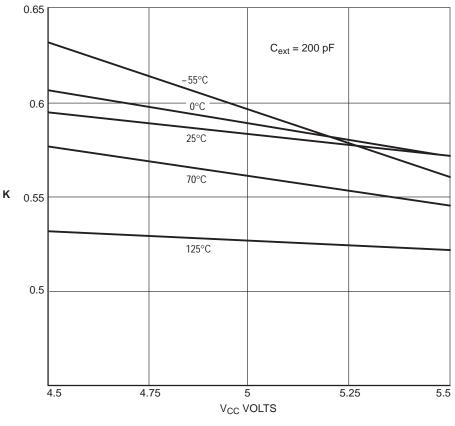


Figure 9.

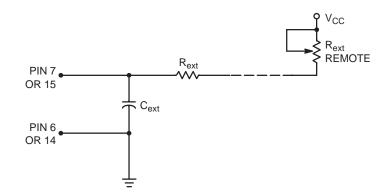


Figure 10. LS123 Remote Trimming Circuit

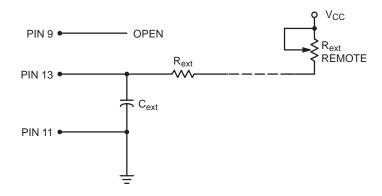
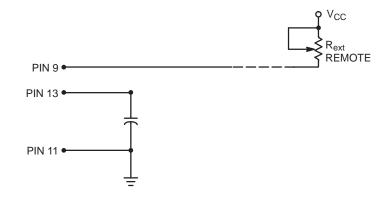
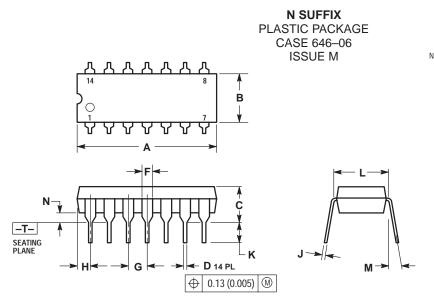


Figure 11. LS122 Remote Trimming Circuit Without Rext





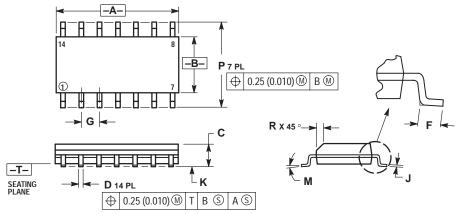
## **PACKAGE DIMENSIONS**



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: INCH.
DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
DIMENSION B DOES NOT INCLUDE MOLD FLASH.
ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.715	0.770	18.16	18.80	
В	0.240	0.260	6.10	6.60	
С	0.145	0.185	3.69	4.69	
D	0.015	0.021	0.38	0.53	
F	0.040	0.070	1.02	1.78	
G	0.100	BSC	2.54 BSC		
Н	0.052	0.095	1.32	2.41	
J	0.008	0.015	0.20	0.38	
K	0.115	0.135	2.92	3.43	
L	0.290	0.310	7.37	7.87	
Μ		10°		10°	
Ν	0.015	0.039	0.38	1.01	

**D SUFFIX** PLASTIC SOIC PACKAGE CASE 751A-03 ISSUE F



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.

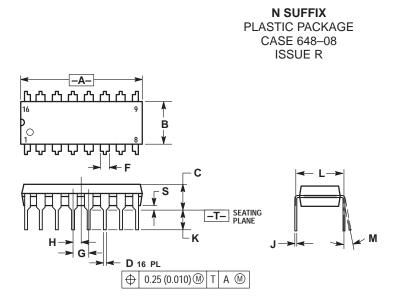
DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

PER SIDE. 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MIN MAX		MAX	
Α	8.55	8.75	0.337	0.344	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050 BSC		
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
Μ	0 °	7°	0 °	7°	
Р	5.80	6.20	0.228	0.244	
R	0.25	0.50	0.010	0.019	

## **PACKAGE DIMENSIONS**



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.

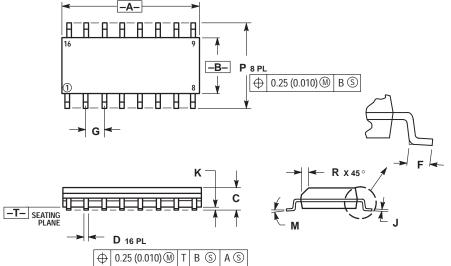
2.

3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

DIMENSION B DOES NOT INCLUDE MOLD FLASH.
ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIMETERS		
DIM	MIN MAX		MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
К	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
Μ	0°	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

**D SUFFIX** PLASTIC SOIC PACKAGE CASE 751B-05 **ISSUE J** 



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- 2.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. 3.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. 4.
- DIMENSION D DOES NOT INCLUDE DAMBAR 5. PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MIN MAX		MAX	
Α	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050 BSC		
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
Μ	0 °	7°	0 °	7°	
Р	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

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